

ABSTRACT OF THE DISCLOSURE

A component mounter for picking up a component and mounting it on a board using a transfer head. A position of solder paste printed on an electrode on a board is previously measured and a measurement result is stored. Mounting coordinates for mounting the component using the transfer head is calculated based on this measurement result. In the mounting operation, the transfer head is controlled using mounting coordinates determined based on the solder printing position so as to mount the component on each electrode on the board. This prevents the occurrence of positional deviation between the mounted component and printed solder paste. Defective mounting, which may occur in a reflow process due to positional deviation, is thus preventable.